

A

A

B

B

C

C

D

D

# MPPT Solar Converter

## SOLAR CAR 2021

### REV 2

Title <b>COVER</b>		Badgerloop Electrical 133 Engineering Research Building 1500 Engineering Drive Madison, Wi 53706	
Engineer: Shelby Riggleman	Revision:1	Date: 4/15/2022 Time: 10:37:09 AM Sheet 1 of 10	
File: cover.SchDoc			

# Connectors

A

A

B

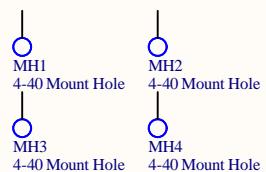
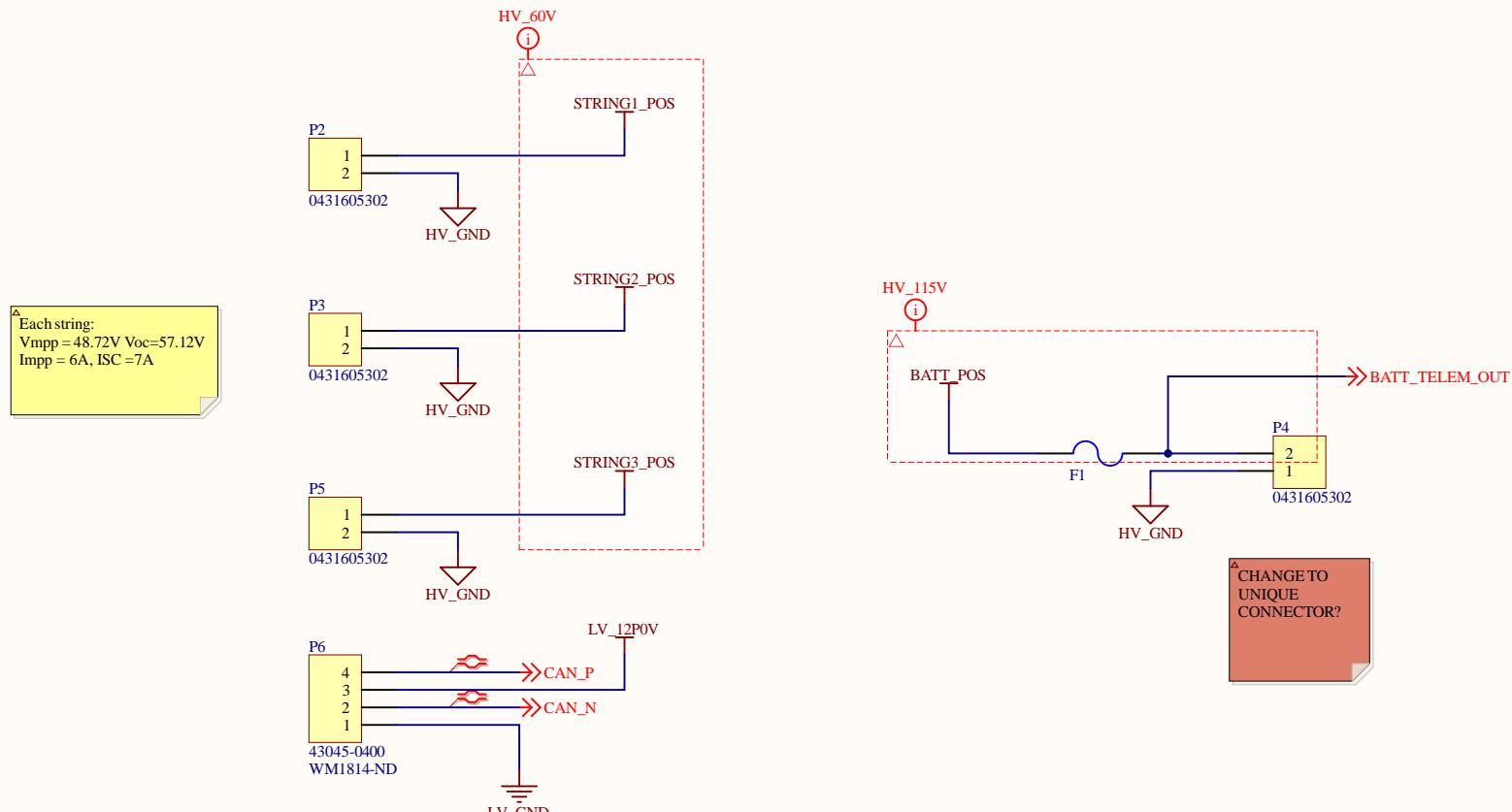
B

C

C

D

D

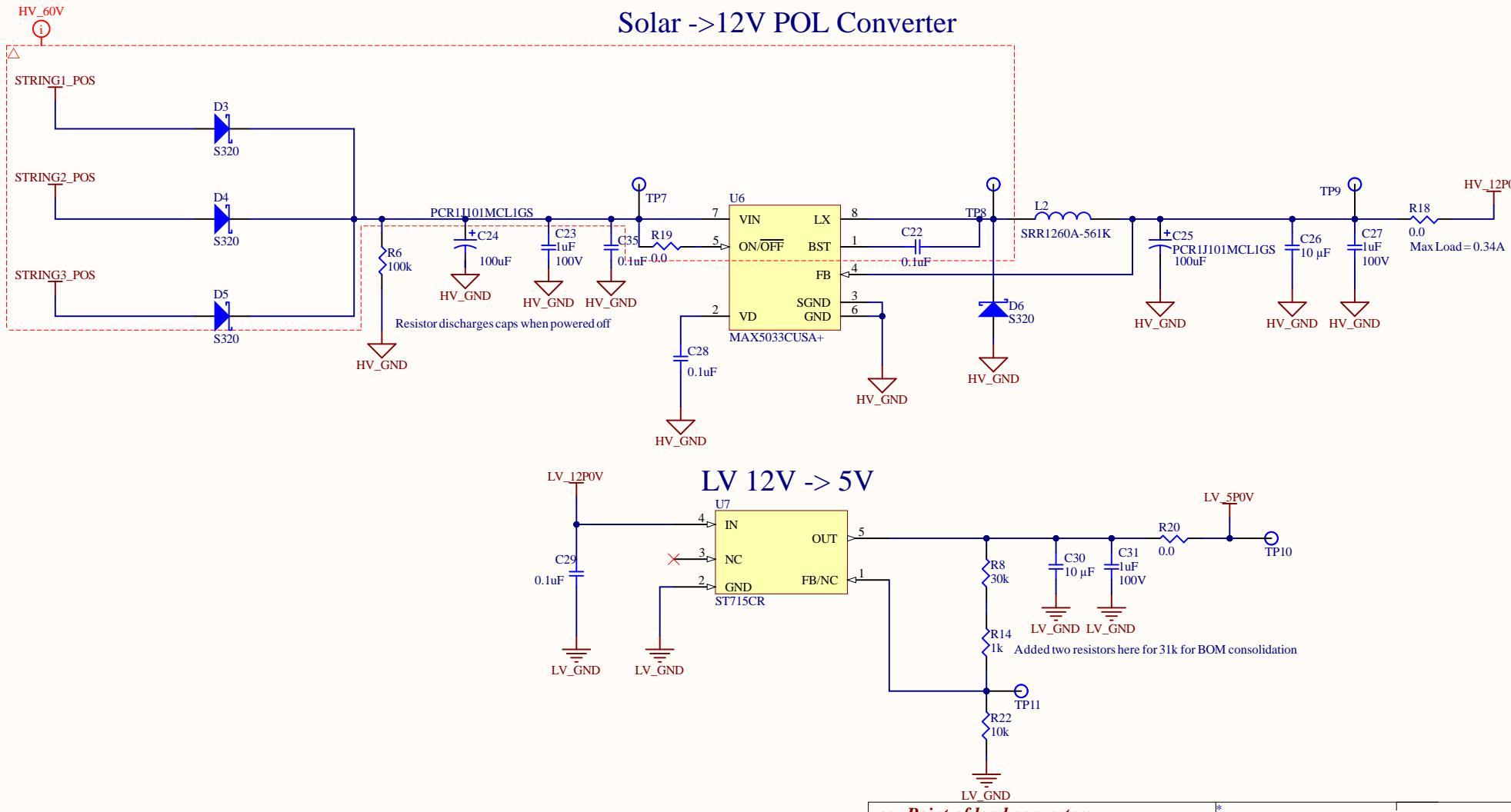


Title <b>Connectors</b>	
Engineer: Shelby Riggelman	Revision: 1
Date: 4/15/2022	Time: 10:37:10 AM Sheet 2 of 10
File: Connectors.SchDoc	

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**LOOP**

# Point of Load Converters

Solar ->12V POL Converter



Title **Point of load converters**

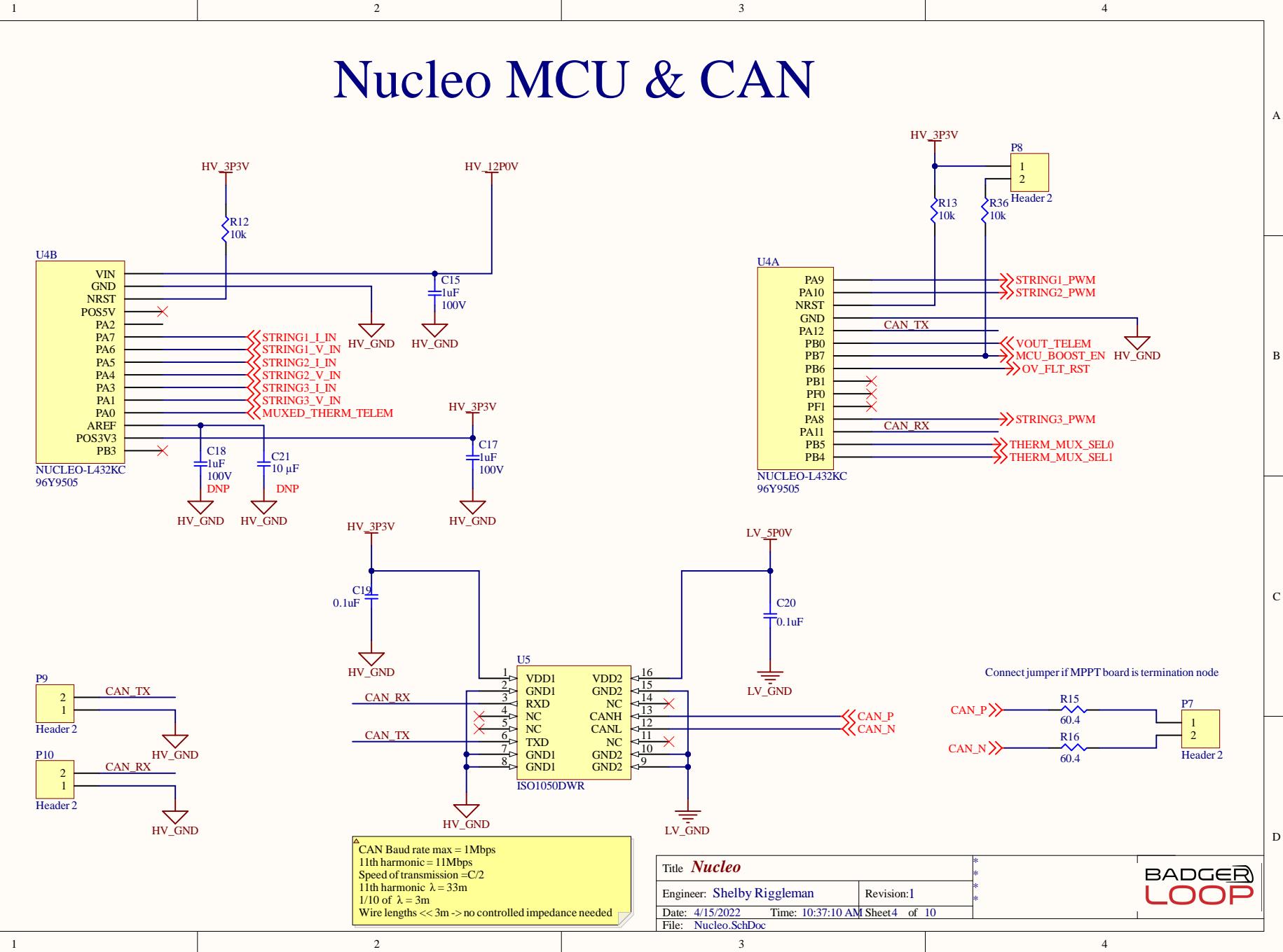
Engineer: Shelby Riggelman

Revision: 1

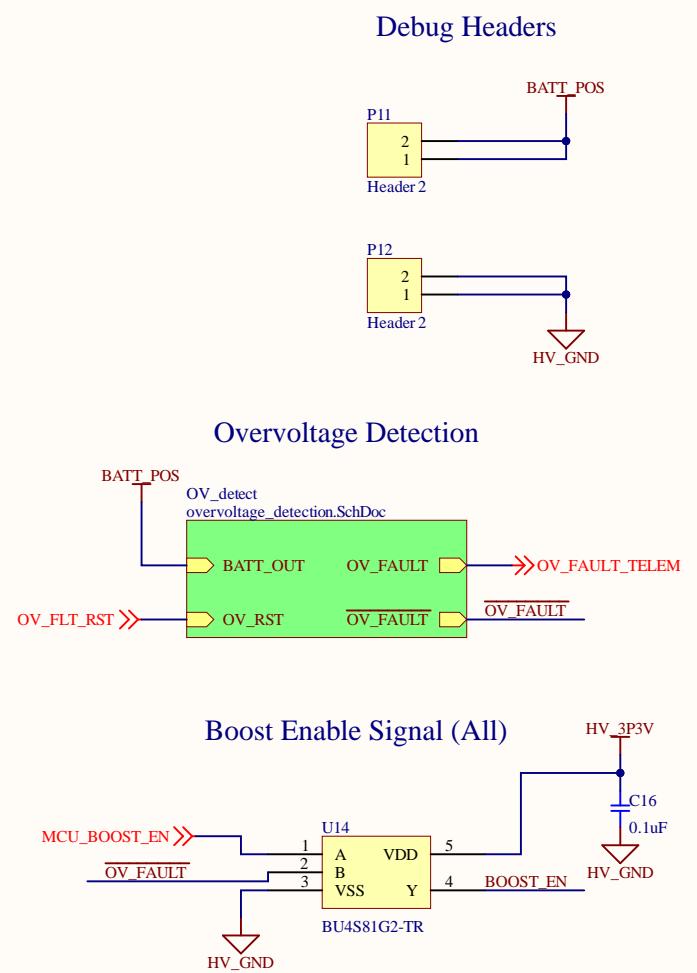
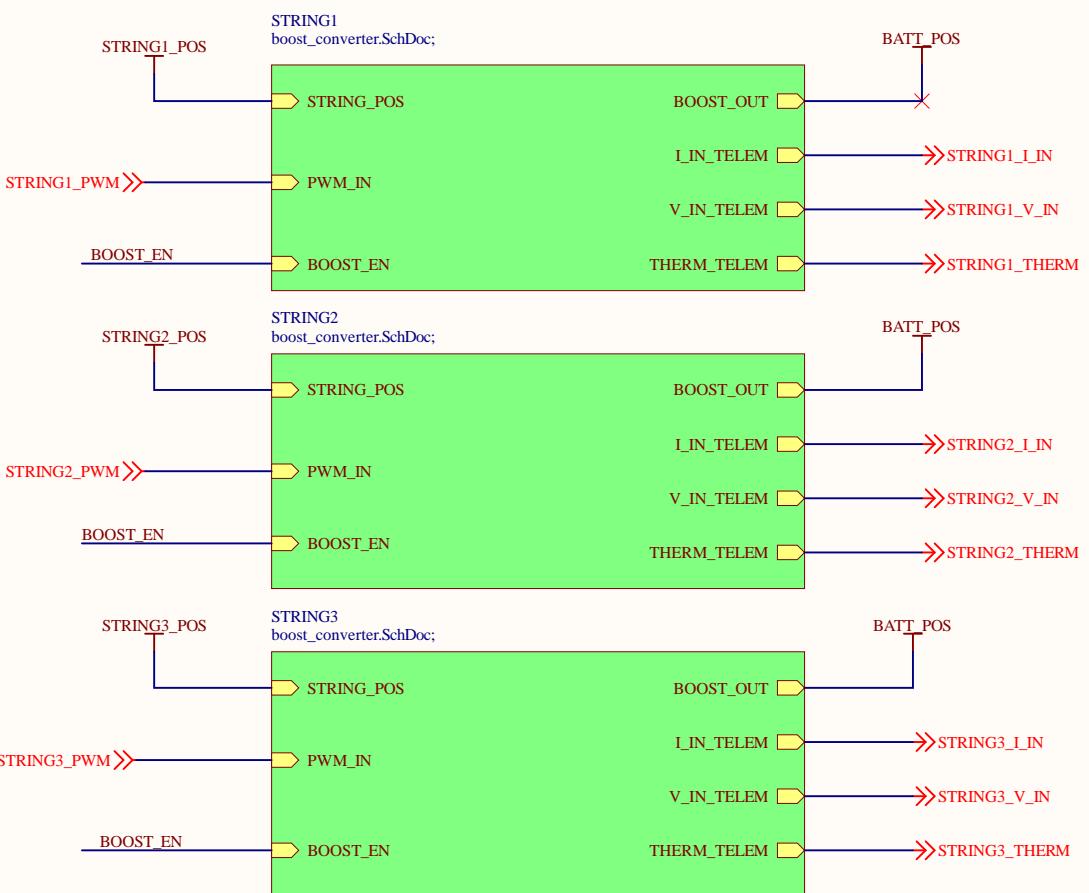
Date: 4/15/2022 Time: 10:37:10 AM Sheet 3 of 10

File: POL\_converter.SchDoc

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# Solar Strings MPPTs



Title <b>Boost Strings</b>	
Engineer: <b>Shelby Riddleman</b>	Revision: <b>I</b>
Date: <b>4/15/2022</b>	Time: <b>10:37:11 AM</b>
File: <b>color_hex_strings.SchDoc</b>	Sheet <b>5</b> of <b>10</b>

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# Solar Boost Converter

1

2

3

4

A

B

C

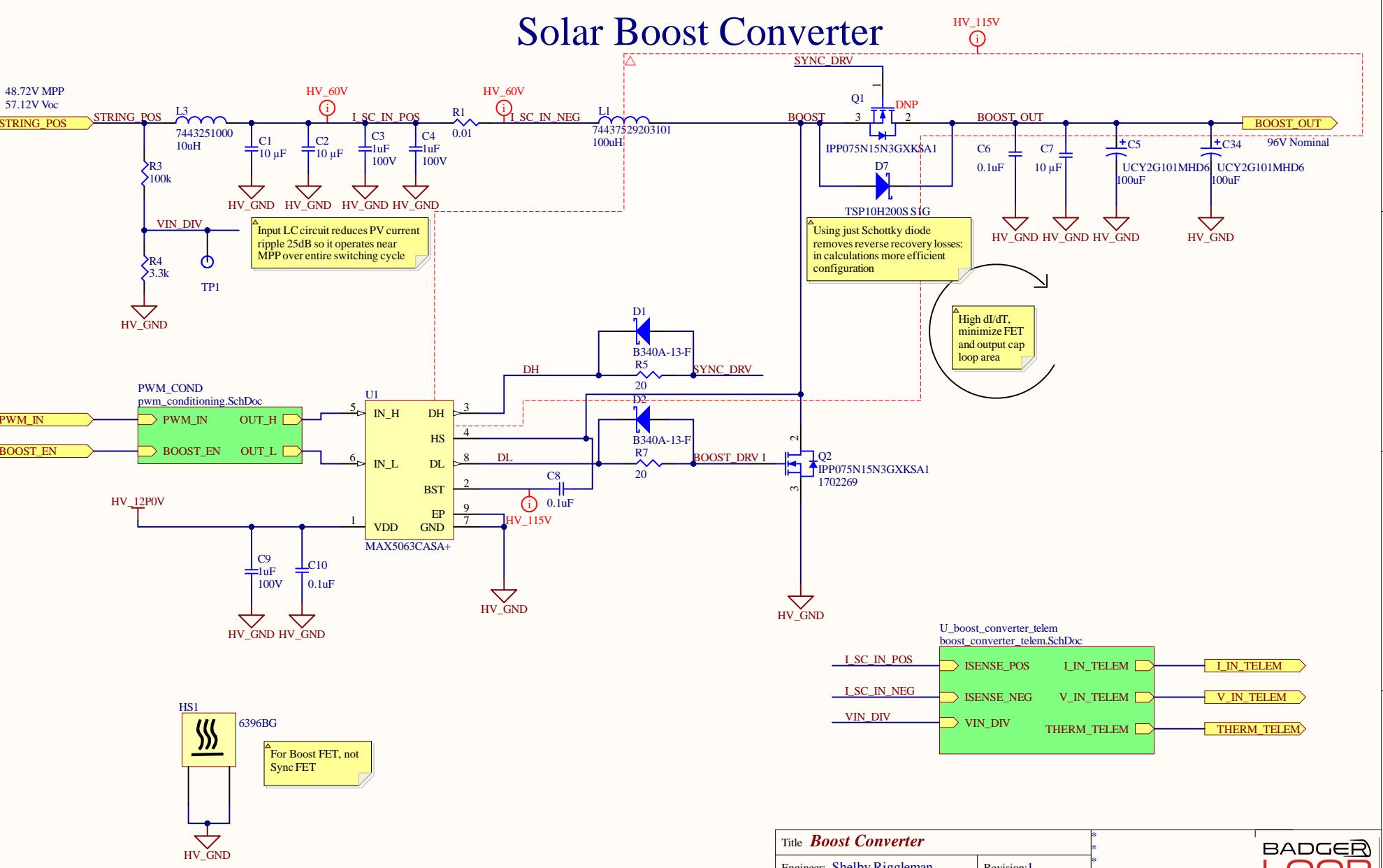
D

A

B

C

D

Title **Boost Converter**

Engineer: Shelby Riggelman

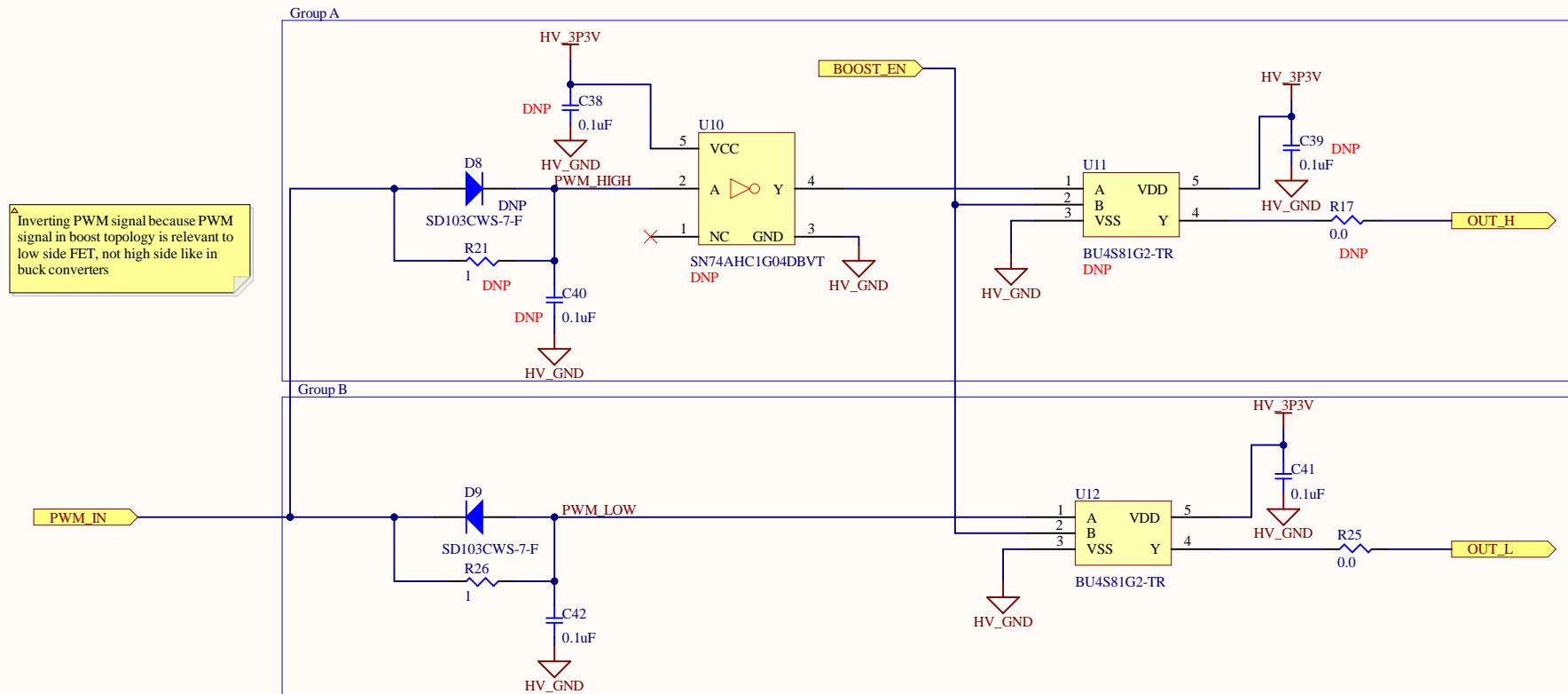
Revision: 1

Date: 4/15/2022 Time: 10:37:11 AM Sheet 6 of 10

File: boost\_converter.SchDoc

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# PWM Conditioning



Gate Driver	Sync. Config (2 FETS):	Async. Config (FET + Diode)
MAX5063A/MAX5063C	Populate all components	DNP Group A, or remove OUT_H resistor Short out PWM_LOW RC resistor
MIC4102	DNP Group B, or remove OUT_L resistor Short out PWM_HIGH RC resistor	DNP Group B, or remove OUT_L resistor Short out PWM_HIGH RC resistor
MIC4103	Populate all components	DNP Group A, or remove OUT_H resistor Short out PWM_LOW RC resistor

Title **PWM Conditioning**

Engineer: Shelby Riggelman

Revision: 1

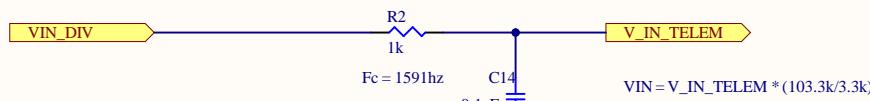
Date: 4/15/2022 Time: 10:37:11 AM Sheet 7 of 10

File: pwm\_conditioning.SchDoc

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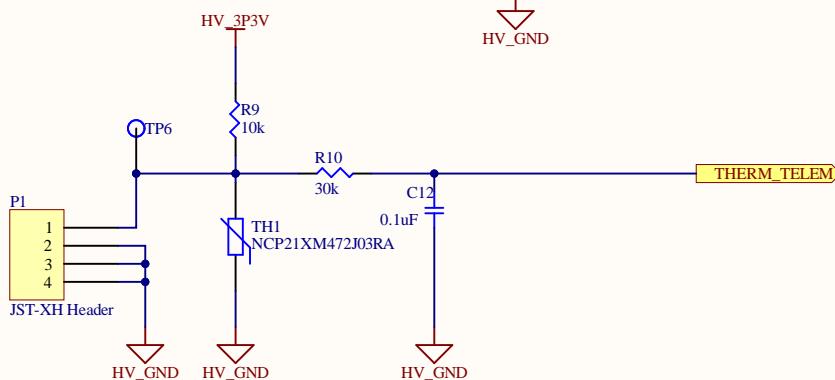
# Solar Boost Converter Telemetry

## String Input Voltage

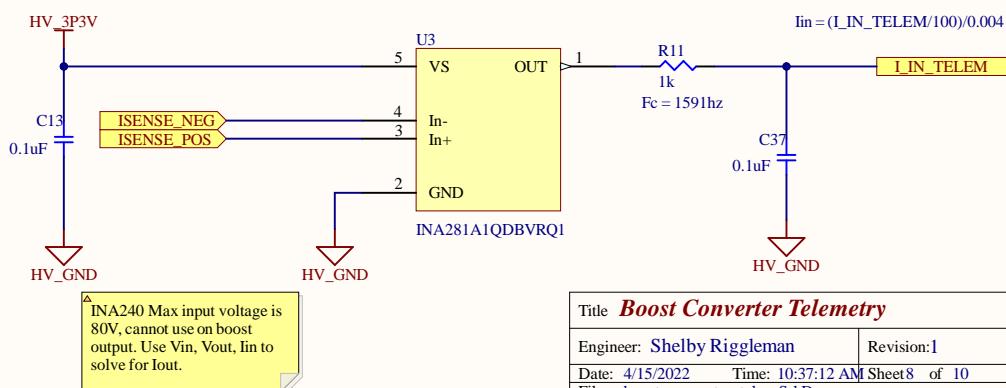


△ UPDATE COMPONENTS TO CREATE CORNER FREQUENCY HIGHER THAN CONTROL LOOP UPDATE RATE UPON TESTING

## Thermistor Output



## String Input Current



△ INA240 Max input voltage is 80V, cannot use on boost output. Use Vin, Vout, Iin to solve for Iout.

Title **Boost Converter Telemetry**

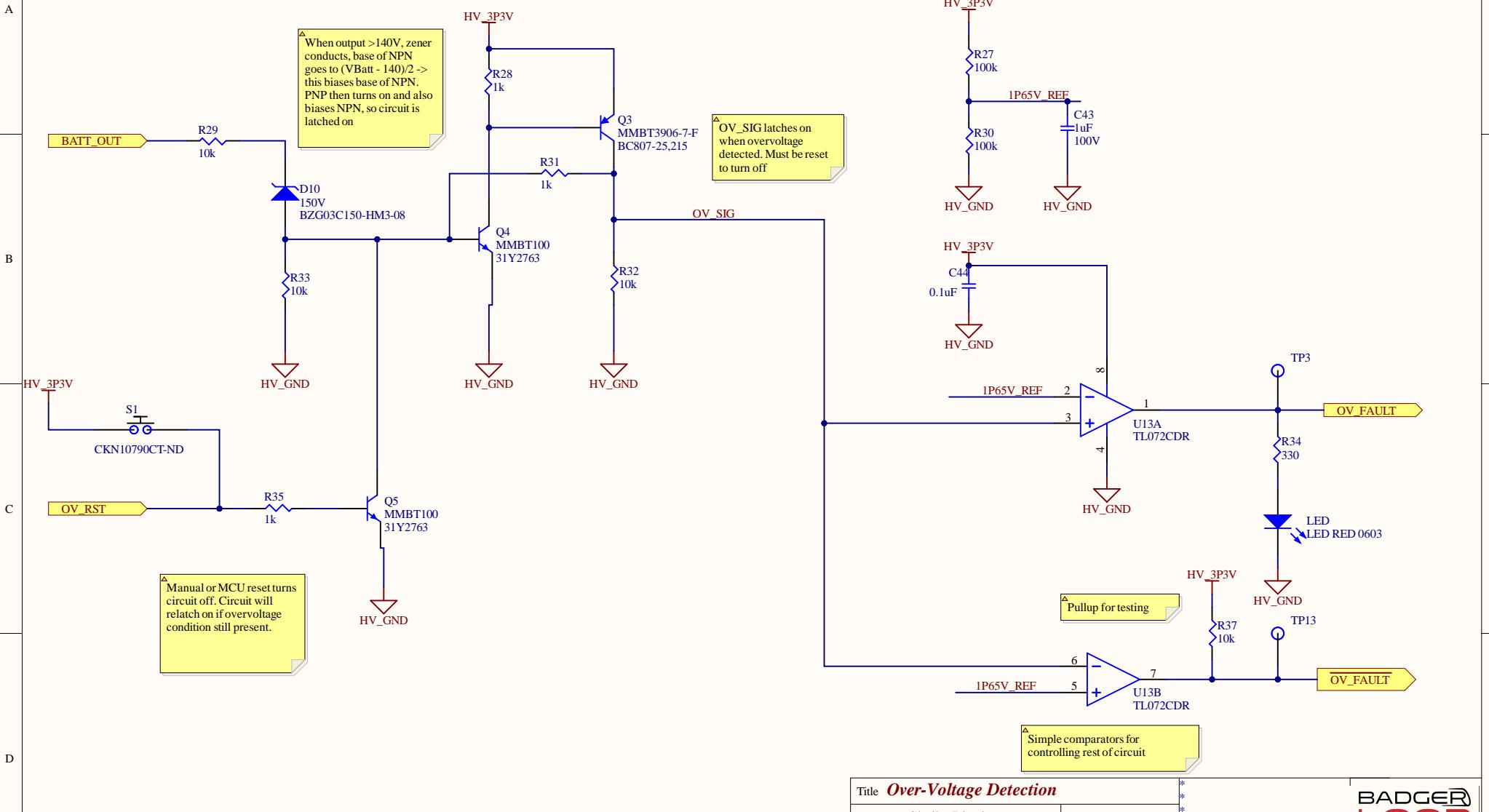
Engineer: Shelby Riggelman Revision: 1

Date: 4/15/2022 Time: 10:37:12 AM Sheet 8 of 10

File: boost\_converter\_telem.SchDoc

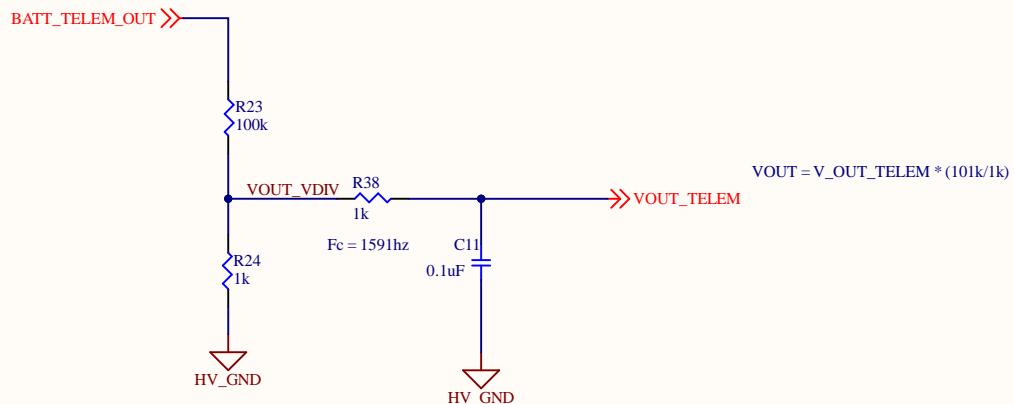
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# Overvoltage Detection

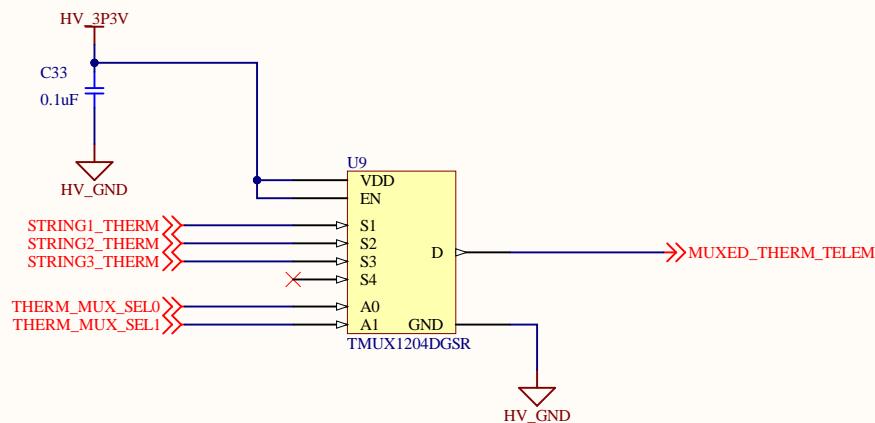


# Global Telemetry

## Output (Battery) Voltage



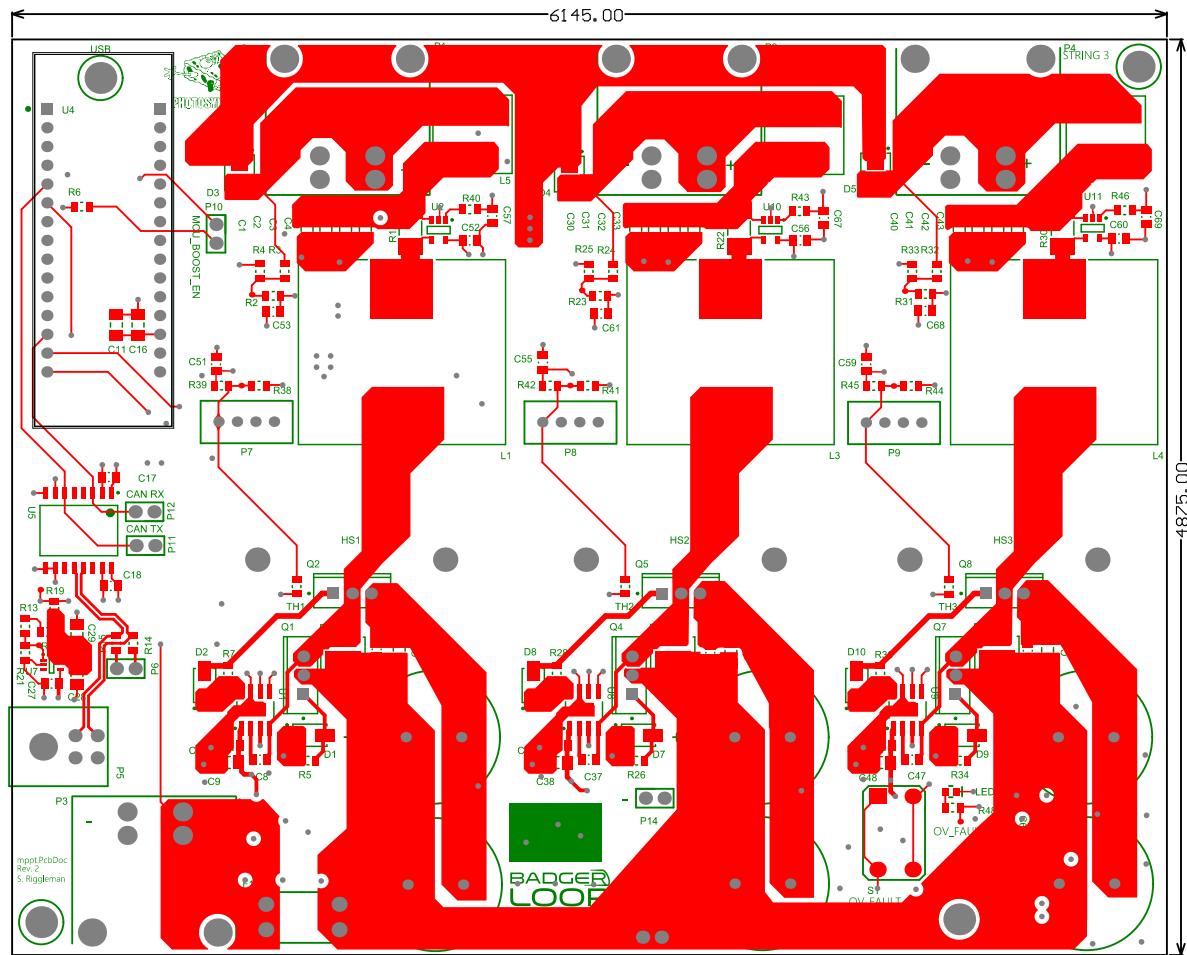
## String Thermistor Telem (Muxed)



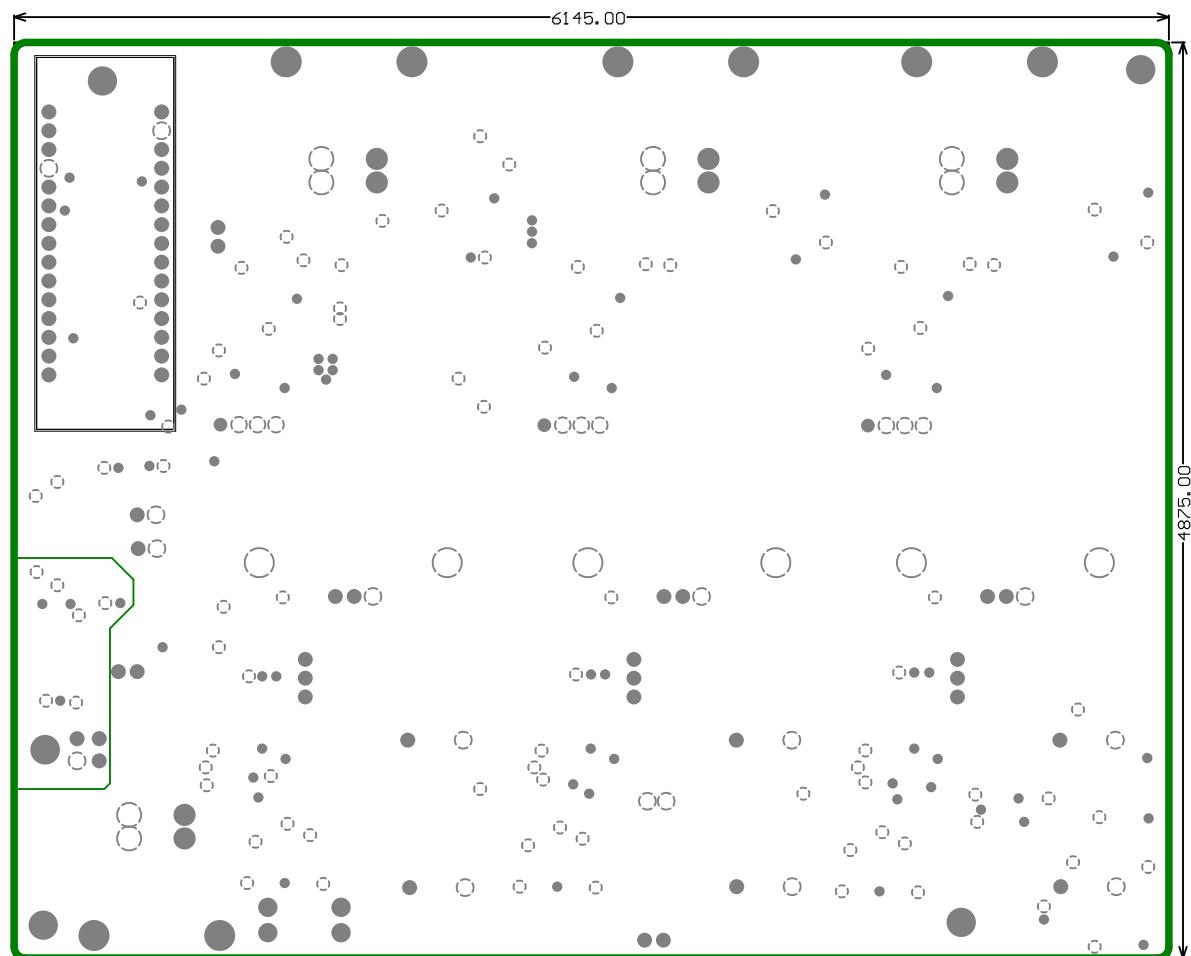
Title <b>Global Telemetry</b>	
Engineer: Shelby Riggelman	Revision: 1
Date: 4/15/2022	Time: 10:37:13 AM Sheet 10 of 10
File: global_telem.SchDoc	

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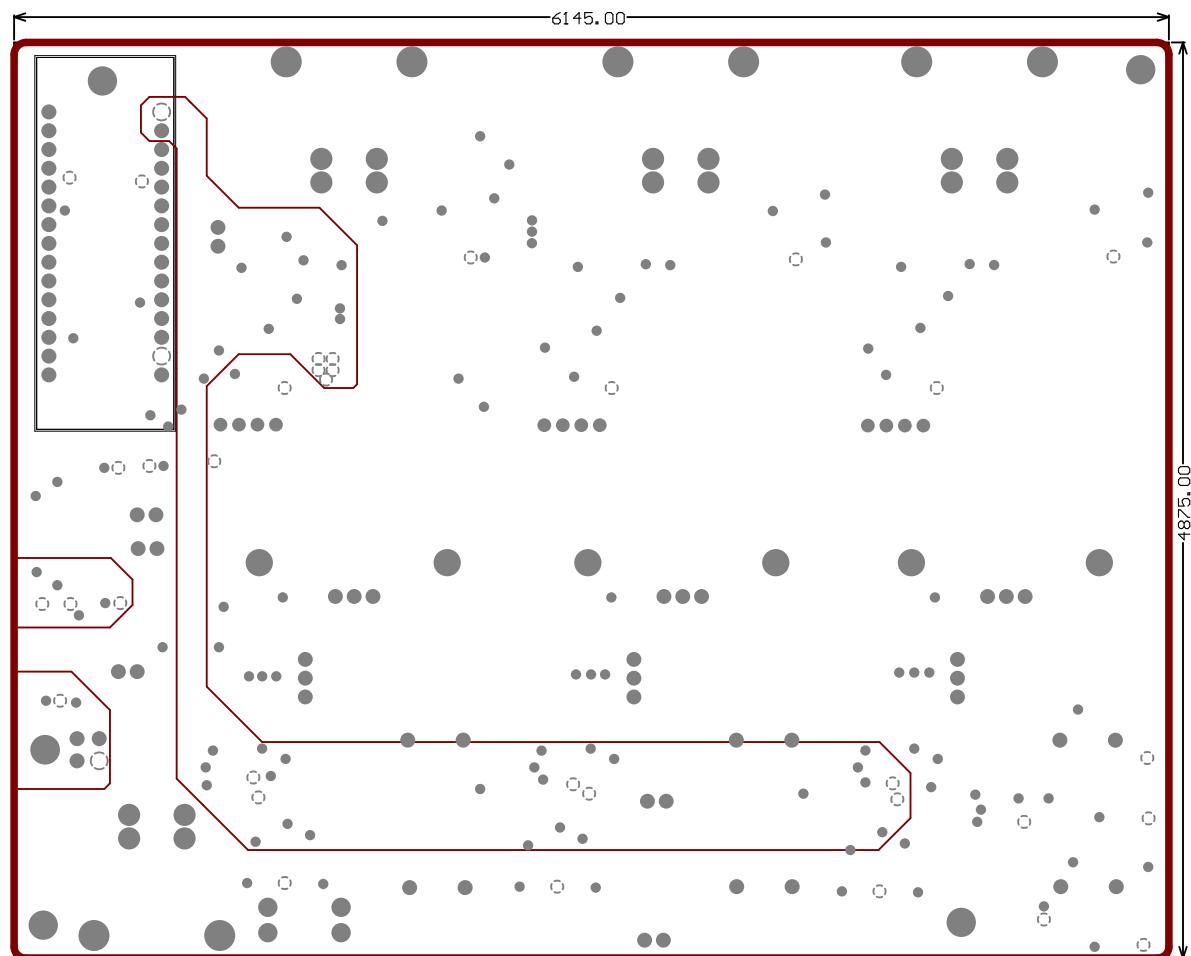
Layer	Name	Material	Thickness	Constant	Board Layer	Stack
	Top Overlay					
	Top Solder	Solder Resist	0.40mil	3.5		
1	Top Layer		1.40mil			
	Dielectric 2	PP-006	2.80mil	4.1		
2	Layer 1	CF-004	1.38mil			
	Dielectric 1	FR-4	12.60mil	4.8		
3	Layer 2	CF-004	1.38mil			
	Dielectric 3	PP-006	2.80mil	4.1		
4	Bottom Layer		1.40mil			
	Bottom Solder	Solder Resist	0.40mil	3.5		
	Bottom Overlay					



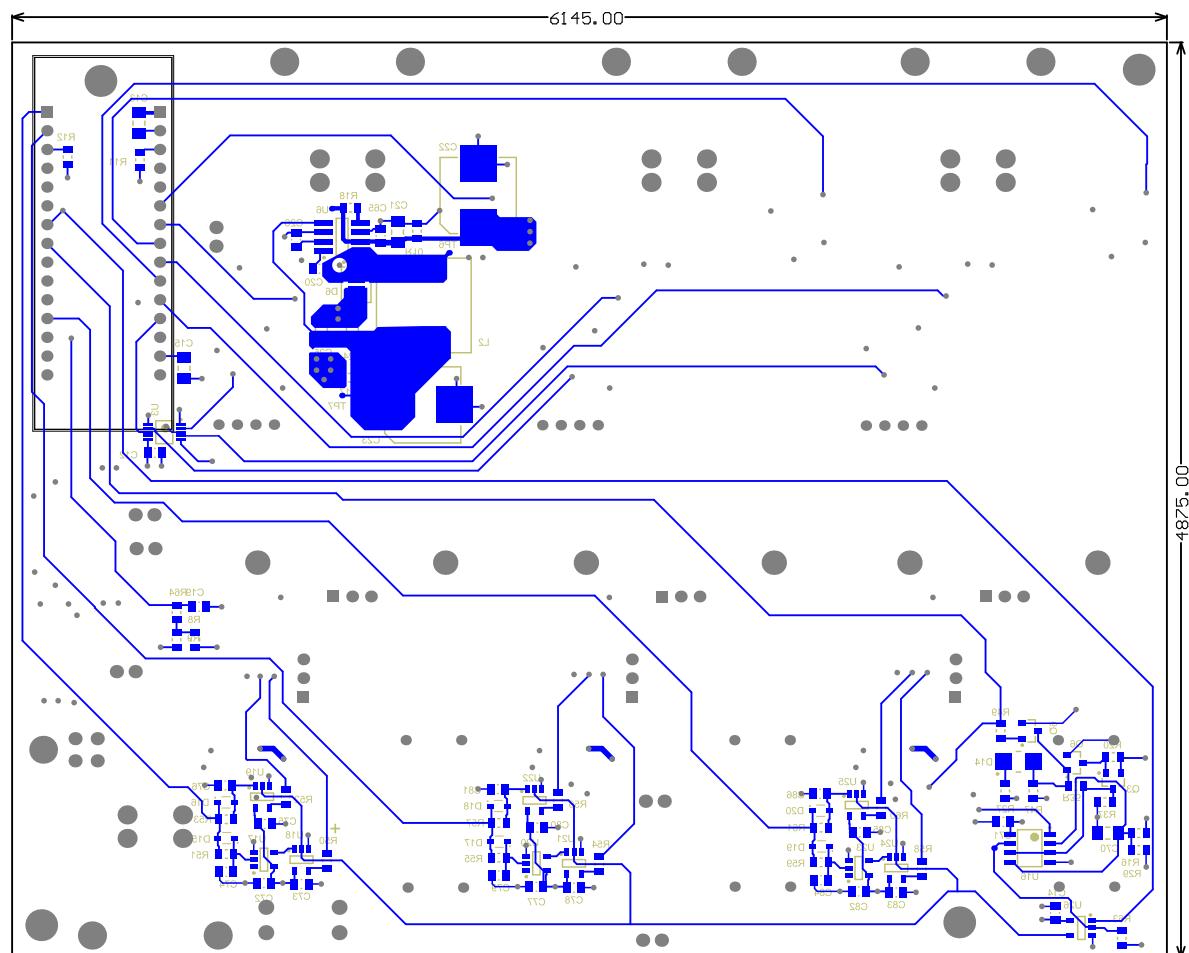
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 2	PP-006	2.80mil	4.1	
2	Layer 1	CF-004	1.38mil		
	Dielectric 1	FR-4	12.60mil	4.8	
3	Layer 2	CF-004	1.38mil		
	Dielectric 3	PP-006	2.80mil	4.1	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 2	PP-006	2.80mil	4.1	
2	Layer 1	CF-004	1.38mil		
	Dielectric 1	FR-4	12.60mil	4.8	
3	Layer 2	CF-004	1.38mil		
	Dielectric 3	PP-006	2.80mil	4.1	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
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2	Layer 1	CF-004	1.38mil		
	Dielectric 1	FR-4	12.60mil	4.8	
3	Layer 2	CF-004	1.38mil		
	Dielectric 3	PP-006	2.80mil	4.1	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
1	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
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2	Layer 1	CF-004	1.38mil		
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3	Layer 2	CF-004	1.38mil		
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4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

